HITANO ENTERPRISE CORP.®

1. INTRODUCTION

HITANO open-mode series MLCC is designed by a special internal electrode pattern, which can reduce voltage concentrations by distributing voltage gradients throughout the entire capacitor. This special design also affords open-mode pattern to prevent circuit leakage when focused to failure in a board flex situation.

2. FEATURES

a. Medium voltage in a given case size.
b. Circuit open during product cracking.
c. High stability and reliability.
d. RoHS compliant.

3. APPLICATIONS

a. High current applications.
b. Power supply and related industries.
c. The other mechanical stress concerned products.

4. HOW TO ORDER

OP	0805	B	101	K	251	E	X	G
Series	**Size**	**Dielectric**	**Capacitance**	**Tolerance**	**Rated Voltage**	**Packaging**	**Thickness**	**Control Code**
Table 1	Table 2	Table 3	Table 4	Table 5	Table 6	Table 7	Table 8	Table 9

Table 1 Series

Code	Description
OP	Open-mode design series

Table 2 Size

Code	Description	Code	Description	Code	Description
15	0402 (1005)	32	1210 (3225)	52	2211 (5728)
18	0603 (1608)	42	1808 (4520)	55	2220 (5750)
21	0805 (2012)	43	1812 (4532)	56	2225 (5763)
31	1206 (3216)	46	1825 (4563)		

Table 3 Dielectric Material Characteristics

Code	Description	Code	Description
X	X7R		

Table 4 Capacitance Rule Code

Code	Description	Code	Description
R47	0.47pF	102	$102=10x10^2=1000pF$
0R5	0.5pF	104	$104=10x10^4=100nF$
100	$100=10x10^0=10pF$	106	$106=10x10^6=10\mu F$

Table 5 Tolerance

Code	Description	Code	Description	Code	Description
A	±0.05 pF	J	±5 %	X	+10%~+20%
B	±0.10 pF	K	±10 %		
C	±0.25 pF	L	0% ~ +10%		
D	±0.50 pF	M	±20 %		
F	±1 %	N	-5% ~ +10%		
G	±2 %	P	±0.02 pF		
H	±3 %	Q	±0.03 pF		
I	-10% ~ 0%	Z	-20% ~ +80%		

Table 6 Rated Voltage

Code	Description	Code	Description	Code	Description
250	25Vdc	201	200Vdc	501	500Vdc
500	50Vdc	251	250Vdc	631	630Vdc
101	100Vdc	401	400Vdc		

Table 7 Packaging Type

Code	Description	Code	Description
B	Bulk	T	Tray package
E	Tape and 7” Reel, Embossed Tape	P	Tape and 7” Reel, Paper Tape
K	Tape and 10” Reel, Embossed Tape	D	Tape and 10” Reel, Paper Tape
L	Tape and 13” Reel, Embossed Tape	G	Tape and 13” Reel, Paper Tape

Table 8 Thickness Description

Code	Description	Code	Description	Code	Description
A	0.60 ± 0.10 mm	I	1.25 ± 0.20 mm	Q	0.50 +0.02/-0.05 mm
B	0.8 + 0.15/-0.10 mm	J	1.15 ± 0.15 mm	R	3.10 ± 0.30 mm
C	1.25 ± 0.10 mm	K	0.50 ± 0.20 mm	S	0.80 ± 0.07 mm
D	1.40 ± 0.15 mm	L	0.30 ± 0.03 mm	T	0.85 ± 0.10 mm
E	1.60 ± 0.20 mm	M	0.95 ± 0.10 mm	U	0.50 ± 0.10 mm
F	2.00 ± 0.20 mm	N	0.50 ± 0.05 mm	V	0.20 ± 0.02 mm
G	2.50 ± 0.30 mm	O	3.50 ± 0.20 mm	X	0.80 ± 0.10 mm
H	2.80 ± 0.30 mm	P	1.60 +0.3/-0.10 mm	Z	0.25 ± 0.03 mm

Table 9 Special Control Code

Code	Description
G	RoHS Compliant
E	Soft termination

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5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	Code / T (mm)	M_B (mm)
0805(2012)	2.10±0.20	1.25±0.20	See No.4 Reference Table 8	0.50±0.20
1206(3216)	3.30±0.30	1.60±0.20 1.60 +0.3/-0.1#		0.60±0.20
1210(3225)	3.30±0.40	2.50±0.30		0.75±0.35
1812(4532)	4.60±0.50	3.20±0.30		0.75±0.35

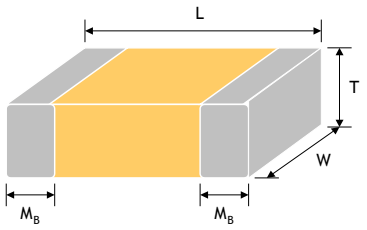

Fig. 5.1 The outline of MLCC

" # " For 1206 size P thickness products.

6. GENERAL ELECTRICAL DATA

Dielectric	X7R
Size	0805, 1206, 1210, 1812
Rated voltage (WVDC)	25V, 50V, 100V, 200V, 250V, 500V, 630V
Capacitance range	100pF ~ 1μF
Capacitance tolerance	Reference to Table 5
Tan δ	≤2.5%~≤10.0%
Capacitance & Tan δ Test condition	Measured at the condition of 30~70% related humidity
	Preconditioning for Class II MLCC : Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement
	1.0±0.2Vrms, 1.0KHz±10%, at 25°C ambient temperature
Insulation resistance at Ur	≥10GΩ or RxC≥100Ω-F, whichever is smaller
Operating temperature	-55 to +125°C
Capacitance characteristic	±15%
Termination	Cu/Ni/Sn (lead-free termination)

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7. CAPACITANCE RANGE

7-1. X7R

Dimension		0805							1206					
Cap(pF)	code	25V	50V	100V	200V	250V	500V	630V	50V	100V	200V	250V	500V	630V
100	101	X	X	X	X	X	X	X						
120	121	X	X	X	X	X	X	X						
150	151	X	X	X	X	X	X	X	X	X	C	C	C	C
180	181	X	X	X	X	X	X	X	X	X	C	C	C	C
220	221	X	X	X	X	X	X	X	X	X	C	C	C	C
270	271	X	X	X	X	X	X	X	X	X	C	C	C	C
330	331	X	X	X	X	X	X	X	X	X	C	C	C	C
390	391	X	X	X	X	X	X	X	X	X	C	C	C	C
470	471	X	X	X	X	X	X	X	X	X	C	C	C	C
560	561	X	X	X	X	X	X	X	X	X	C	C	C	C
680	681	X	X	X	X	X	X	X	X	X	C	C	C	C
820	821	X	X	X	X	X	X	X	X	X	C	C	C	C
1000	102	X	X	X	X	X	X	X	X	X	C	C	C	C
1200	122	X	X	X	X	X	X	X	X	X	C	C	C	C
1500	152	X	X	X	X	X	X	X	X	X	C	C	C	C
1800	182	X	X	X	X	X	X	X	X	X	C	C	C	C
2200	222	X	X	X	X	X	X	X	X	X	C	C	C	C
2700	272	X	X	X	X	X	X	X	X	X	C	C	C	C
3300	332	X	X	X	X	X	X	X	X	X	C	C	C	C
3900	392	X	X	X	X	X	X	X	X	X	C	C	C	C
4700	472	X	X	X	X	X	C	C	X	X	C	C	C	C
5600	562	X	X	X	C	C	C	C	X	X	C	C	C	C
6800	682	X	X	X	C	C	C	C	X	X	C	C	C	C
8200	822	X	X	X	C	C	C	C	X	X	C	C	C	C
10000	103	X	X	X	C	C	C	C	X	X	C	C	C	C
12000	123	X	X	X	C	C			X	X	C	C	C	C
15000	153	X	X	X	C	C			X	X	C	C	C	C
18000	183	X	X	X	C	C			X	X	C	C	C	C
22000	223	X	X	X	C	C			X	X	C	C	E	E
27000	273	X	X	C					X	X	C	C	E	E
33000	333	X	X	C					X	X	E	E	E	E
39000	393	X	X	C					X	X	E	E		
47000	473	M	M	C					X	X	E	E		
56000	563	M	M	C					X	X	E	E		
68000	683	C	C	C					X	X	E	E		
82000	823	C	C	C					C	C	E	E		
100000	104	C	C	C					C	C	E	E		
120000	124	C	C						C	C				
150000	154	C	C						C	E				
180000	184	C	C						C	E				
220000	224	C	C						C	E				
270000	274								C					
330000	334								C					
390000	394								C					
470000	474								C					
560000	564													
680000	684													
820000	824													

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7. CAPACITANCE RANGE

7-1. X7R

Dimension		1210					1812				
Cap(pF)	code	100V	200V	250V	500V	630V	100V	200V	250V	500V	630V
100	101										
120	121										
150	151										
180	181										
220	221										
270	271										
330	331										
390	391										
470	471										
560	561										
680	681										
820	821										
1000	102	M	M	M	C	C	C	C	C	C	C
1200	122	M	M	M	C	C	C	C	C	C	C
1500	152	M	M	M	C	C	C	C	C	C	C
1800	182	M	M	M	C	C	C	C	C	C	C
2200	222	M	M	M	C	C	C	C	C	C	C
2700	272	M	M	M	C	C	C	C	C	C	C
3300	332	M	M	M	C	C	C	C	C	C	C
3900	392	M	M	M	C	C	C	C	C	C	C
4700	472	M	M	M	C	C	C	C	C	C	C
5600	562	M	M	M	C	C	C	C	C	C	C
6800	682	M	M	M	C	C	C	C	C	C	C
8200	822	M	M	M	C	C	C	C	C	C	C
10000	103	M	M	M	C	C	C	C	C	C	C
12000	123	M	M	M	C	C	C	C	C	C	C
15000	153	M	M	M	C	C	C	C	C	C	C
18000	183	M	M	M	C	C	C	C	C	C	C
22000	223	M	M	M	C	C	C	C	C	C	C
27000	273	M	M	M	C	C	C	C	C	C	C
33000	333	M	M	M	E	E	C	C	C	C	C
39000	393	M	M	M	E	E	C	C	C	C	C
47000	473	M	C	C	E	E	C	C	C	C	C
56000	563	M	C	C	E	E	C	C	C	F	F
68000	683	M	E	E	E	E	C	C	C	F	F
82000	823	M	E	E			C	C	C	F	F
100000	104	M	E	E			C	C	C	F	F
120000	124	M	E	E			C	C	C		
150000	154	C	G	G			C	F	F		
180000	184	C	G	G			C	F	F		
220000	224	C	G	G			C	F	F		
270000	274	E					C	F	F		
330000	334	E					C	F	F		
390000	394	G					C	F	F		
470000	474	G					F	F	F		
560000	564	G					F				
680000	684						F				
820000	824						F				
1000000	105						F				

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8. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

<table>
<tr><th>No.</th><th>Item</th><th>Test Condition</th><th>Requirements</th></tr>
<tr><td>1.</td><td>Visual and Dimensions</td><td>---</td><td>* No remarkable defect.
* Dimensions to confirm to individual specification sheet.</td></tr>
<tr><td>2.</td><td>Capacitance</td><td rowspan="2">* 1.0±0.2Vrms, 1kHz±10%
* Before initial measurement (Class II only) : To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp</td><td>* Shall not exceed the limits given in the detailed spec.</td></tr>
<tr><td>3.</td><td>Q/ D.F. (Dissipation Factor)</td><td>
<table>
<tr><th>Dielectric</th><th>Q/D.F.</th><th>Remark</th></tr>
<tr><td rowspan="4">Class II</td><td>D.F.≤2.5%</td><td>X7R items</td></tr>
<tr><td>D.F.≤3.5%</td><td>X7R 0805≥0.082μF, 1206≥0.47μF, ALL 25V/50V</td></tr>
<tr><td>D.F.≤5.0%</td><td>X7R 0805≥0.12μF</td></tr>
<tr><td>D.F.≤10.0%</td><td>X7R 0805≥0.27μF</td></tr>
</table>
</td></tr>
<tr><td>4.</td><td>Temperature Coefficient</td><td>* With no electrical load.
<table>
<tr><th>T.C.</th><th>Operating Temp.</th></tr>
<tr><td>X7R</td><td>-55~125°C at 25°C</td></tr>
</table>
</td><td>
<table>
<tr><th>T.C.</th><th>Capacitance Change</th></tr>
<tr><td>X7R</td><td>Within ±15%</td></tr>
</table>
</td></tr>
<tr><td>5.</td><td>Insulation Resistance</td><td>
<table>
<tr><th>Rated Vol.(V)</th><th>Apply Voltage</th><th>Test Condition</th></tr>
<tr><td>≤100</td><td>1 times of U_R</td><td>Max. 120 sec.</td></tr>
<tr><td>100<V≤500</td><td>1 times of U_R</td><td>60 sec.</td></tr>
<tr><td>>500</td><td>500Vdc</td><td>60 sec.</td></tr>
</table>
</td><td>
<table>
<tr><th>Dielectric</th><th>Requirements</th></tr>
<tr><td>Class II</td><td>≥10GΩ or RxC≥100Ω-F, whichever is smaller</td></tr>
</table>
</td></tr>
<tr><td>6.</td><td>Solderability</td><td>* Solder temperature : 235±5°C for (0805~1210).
* Solder temperature : 245±5°C for (1812).
* Dipping time : 2±0.5 sec.</td><td>* 75% min. coverage of all metalized area.</td></tr>
<tr><td>7.</td><td>Dielectric Strength</td><td>
<table>
<tr><th>Rated Vol.(V)</th><th>Condition</th></tr>
<tr><td>≤100</td><td>2.5 times of U_R</td></tr>
<tr><td>100<V≤250</td><td>2.0 times of U_R</td></tr>
<tr><td>250<V≤500</td><td>1.5 times of U_R</td></tr>
<tr><td>=630</td><td>1.2 times of U_R</td></tr>
</table>
* Duration : 1 to 5 sec.
* Charge and discharge current less than 50mA.
</td><td>* No evidence of damage or flashover during test.</td></tr>
<tr><td>8.</td><td>Resistance to Soldering Heat</td><td>* Solder temperature : 260±5°C.
* Dipping time : 10±1 sec.
* Preheating : 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder.
* Before initial measurement (Class II only) : Perform 150 +0/-10°C for 1 hr and then set for 48±4 hrs at room temp.
* Measurement to be made after keeping at room temp. for 48±4 hrs (Class II).</td><td>* No remarkable damage.
* Cap. Change :
X7R : Within ±7.5%.
* Q/D.F. & I.R. : To meet the initial requirement.
* 25% max. leaching on each edge.</td></tr>
<tr><td>9.</td><td>Temperature Cycle</td><td>* Conduct the five cycles according to the temperatures and time.
<table>
<tr><th>Step</th><th>Temp.(°C)</th><th>Time(min.)</th></tr>
<tr><td>1</td><td>Min. operating temp. +0/-3</td><td>30±3</td></tr>
<tr><td>2</td><td>Room temp.</td><td>2~3</td></tr>
<tr><td>3</td><td>Max. operating temp. +3/-0</td><td>30±3</td></tr>
<tr><td>4</td><td>Room temp.</td><td>2~3</td></tr>
</table>
* Before initial measurement (Class II only) : Perform 150 +0/-10°C for 1 hr and then set for 48±4 hrs at room temp.
* Measurement to be made after keeping at room temp. for 24±2 hrs (Class I) or 48±4 hrs (Class II).
</td><td>* No remarkable damage.
* Cap. change :
X7R : Within ±7.5%.
* Q/D.F. :
X7R : D.F.≤150% of initial requirement.
* I.R. : To meet the initial requirement.</td></tr>
</table>

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8. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

<table>
<tr><th>No.</th><th>Item</th><th>Test Condition</th><th>Requirements</th></tr>
<tr><td>10.</td><td>Humidity (Damp Heat) Steady State</td><td>* Test temp. : 40±2°C.
* Humidity : 90~95%RH.
* Test time : 500 +24/-0 hrs.
* Measurement to be made after keeping at room temp. for 24±2 hrs 48±4 hrs (Class II).</td><td>* No remarkable damage.
* Cap. change :
X7R : Within ±12.5%.
* Q/D.F. :
X7R : D.F.≤200% of initial requirement.
* I.R. : ≥1GΩ or RxC≥50Ω-F, whichever is smaller.
X7R 100V : ≥1GΩ or RxC≥10Ω-F, whichever is smaller.</td></tr>
<tr><td>11.</td><td>Humidity (Damp Heat) Load</td><td>* Test temp. : 40±2°C.
* Humidity : 90~95% RH.
* Test time : 500 +24/-0hrs.
* To apply voltage : Rated voltage (Max. 500Vdc).
* Measurement to be made after keeping at room temp. for 48±4 hrs (Class II).</td><td>* No remarkable damage.
* Cap. change :
X7R : Within ±12.5%.
* Q/D.F. :
X7R : D.F.≤200% of initial requirement.
* I.R. :≥500MΩ or RxC≥25Ω-F, whichever is smaller.
X7R 100V : ≥500MΩ or RxC≥5Ω-F, whichever is smaller.</td></tr>
<tr><td>12.</td><td>High Temperature Load (Endurance)</td><td>* Test temp. :
C0G, X7R : 125±3°C.
<table>
<tr><th>Dielectric</th><th>Rated Vol.(V)</th><th>Apply Voltage</th></tr>
<tr><td rowspan="3">X7R</td><td>≤100</td><td>2.0 times of U_R</td></tr>
<tr><td>200≤V≤500</td><td>1.5 times of U_R</td></tr>
<tr><td>=630</td><td>1.2 times of U_R</td></tr>
</table>
* Exception items :
<table>
<tr><th>Rated Vol.(V)</th><th>Size</th><th>Cap. Range</th><th>Apply Voltage</th></tr>
<tr><td rowspan="2">100</td><td>0603</td><td>≥0.082μF</td><td rowspan="5">1.5 times of U_R</td></tr>
<tr><td>0805</td><td>≥0.12μF</td></tr>
<tr><td rowspan="3">200 & 250</td><td>0603</td><td>≥0.082μF</td></tr>
<tr><td>1210</td><td>≥0.22μF</td></tr>
<tr><td>1812</td><td>≥0.47μF</td></tr>
</table>
* Test time : 1000 +24/-0 hrs.
* Measurement to be made after keeping at room temp. for 24±2 hrs (Class I) or 48±4 hrs (Class II).</td><td>* No remarkable damage.
* Cap. change :
X7R : Within ±12.5%.
* Q/D.F. :
X7R : D.F.≤200% of initial requirement.
* I.R. : ≥1GΩ or RxC≥50Ω-F, whichever is smaller.
X7R 100V : ≥1GΩ or RxC≥10Ω-F, whichever is smaller.</td></tr>
</table>

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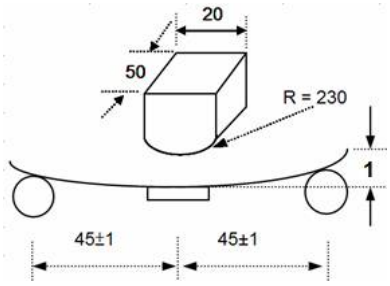
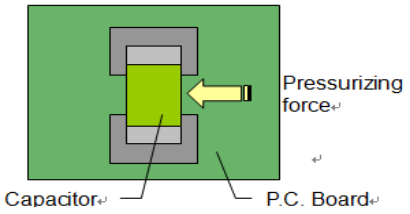
8. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

<table>
<tr><th>No.</th><th>Item</th><th>Test Condition</th><th>Requirements</th></tr>
<tr><td>13</td><td>Resistance to Flexure of Substrate</td><td>* The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1mm per second until the deflection becomes 1mm.
 

Unit : mm</td><td>* No remarkable damage.
<table><tr><th>Dielectric</th><th>Cap. Change</th></tr><tr><td>Class II (X7R)</td><td>Within ±12.5%</td></tr></table>(This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test)</td></tr>
<tr><td>14.</td><td>Adhesive Strength of Termination</td><td>* Capacitors mounted on a substrate. A force of 5N(≤0603) or 10N(>0603) applied perpendicular to the place of substrate and parallel the line joining the center of terminations for 10±1 second.
 
</td><td>* No remarkable damage or removal of the terminations.</td></tr>
<tr><td>15.</td><td>Vibration Resistance</td><td>* Vibration frequency : 10~55 Hz/min.
* Total amplitude : 1.5mm.
* Test time : 6 hrs. (Two hrs each in three mutually perpendicular directions)
* Measurement to be made after keeping at room temp. for 48±4 hrs (Class II).</td><td>* No remarkable damage.
* Cap. change and Q/D.F. : To meet the initial spec.</td></tr>
</table>

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9. PACKAGE DIMENSION AND QUANTITY

Size	Thickness (mm)	Paper tape		Plastic tape	
		7" reel	13" reel	7" reel	13" reel
0201(0603)	0.30±0.03	15k	70k	-	-
	0.30±0.05	15k	-	-	-
	0.30±0.09	15k	-	-	-
0402(1005)	0.50±0.05	10k	50k	-	-
	0.50 +0.02/-0.05	10k	50k	-	-
	0.50±0.20	10k	-	-	-
0603(1608)	0.50±0.10	4k	-	-	-
	0.80±0.07	4k	15k	-	-
	0.80 +0.15/-0.10	4k	15k	-	-
0805(2012)	0.50±0.10	4k	15k	-	-
	0.60±0.10	4k	15k	-	-
	0.80±0.10	4k	15k	-	-
	0.85±0.10	4k	15k	-	-
	1.25±0.10	-	-	3k	10k
	1.25±0.20	-	-	3k	10k
1206(3216)	0.80±0.10	4k	15k	-	-
	0.85±0.10	4k	15k	-	-
	0.95±0.10	-	-	3k	10k
	1.15±0.15	-	-	3k	10k
	1.25±0.10	-	-	3k	10k
	1.60±0.20	-	-	2k	10k
	1.60 +0.30/-0.10	-	-	2k	9k
1210(3225)	0.85±0.10	-	-	3k	10k
	0.95±0.10	-	-	3k	10k
	1.25±0.10	-	-	3k	10k
	1.60±0.20	-	-	2k	-
	2.00±0.20	-	-	1k	6k
	2.50±0.30	-	-	1k	6k
1808(4520)	1.25±0.10	-	-	2k	10k
	1.60±0.20	-	-	2k	8k
	2.00±0.20	-	-	1k	6k
1812(4532)	1.25±0.10	-	-	1k	5k
	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
	2.50±0.30	-	-	0.5k	3k
	2.80±0.30	-	-	0.5k	-
1825(4563)	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
	2.50±0.30	-	-	0.5k	-
	2.80±0.30	-	-	0.5k	-
2220(5750)	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
	2.50±0.30	-	-	0.5k	-
	2.80±0.30	-	-	0.5k	-
2225(5763)	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
	2.50±0.30	-	-	0.5k	-
	2.80±0.30	-	-	0.5k	-

Unit : pcs

9. PACKAGE DIMENSION AND QUANTITY

9.1. EMBOSSED TAPE DIMENSIONS

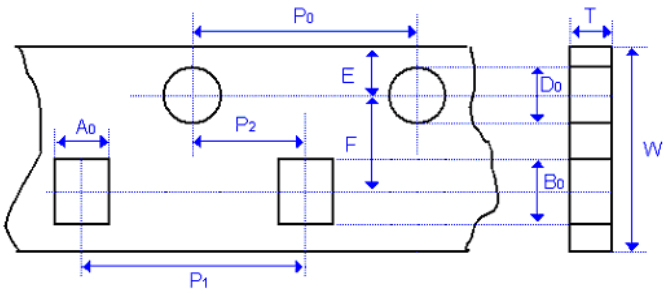


Fig. 9.1 The dimension of paper tape

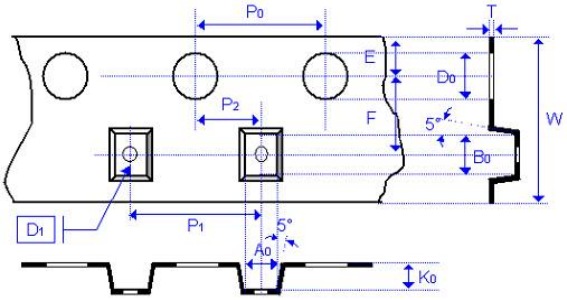


Fig. 9.2 The dimension of plastic tape

Size	0201	0402	0603		0805	
Chip Thickness	0.30±0.03	0.50±0.05 0.50±0.10	0.80±0.07	0.80 +0.15/-0.1	0.80±0.10	1.25±0.10 1.25±0.20
A_0	0.39±0.07	0.70±0.20	1.00 +0.05/-0.10	1.02 +0.05/-0.10	1.50±0.10	<1.65
B_0	0.69±0.07	1.20±0.20	1.80±0.10	1.80±0.10	2.30±0.10	<2.40
T	≤0.50	≤0.80	0.95±0.05	0.97±0.05	0.95±0.05	0.23±0.05
K_0	-	-	-	-	-	<2.50
W	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P_0	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
$10xP_0$	40.00±0.10	40.00±0.10	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20
P_1	2.00±0.05	2.00±0.05	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
P_2	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D_0	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.50 +0.10/-0
D_1	-	-	-	-	-	1.00±0.10
E	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05
Unit :	mm	mm	mm	mm	mm	mm

Size	1206			1210		1812	
Chip Thickness	0.80±0.10	0.95±0.10 1.25±0.10	1.60±0.20 1.60+0.3/-0/1	0.95±0.10 1.25±0.10 1.60±0.20	2.50±0.30	1.25±0.10 1.60±0.20 2.00±0.20	2.50±0.30
A_0	2.00±0.10	<2.00	<2.00	<3.05	<3.10	<3.90	<3.90
B_0	3.50±0.10	<3.60	<3.70	<3.80	<4.00	<5.30	<5.30
T	0.95±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.25±0.05	0.25±0.05
K_0	-	<2.50	<2.50	<2.50	<3.50	<2.50	<3.00
W	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	12.00±0.20	12.00±0.20
P_0	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
$10xP_0$	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.0±0.10	40.00±0.20	40.00±0.20
P_1	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	8.00±0.10	8.00±0.10
P_2	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D_0	1.55±0.05	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0
D_1	-	1.00±0.10	1.00±0.10	1.00±0.10	1.00±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	5.50±0.05	5.50±0.05
Unit :	mm	mm	mm	mm	mm	mm	mm

9. PACKAGE DIMENSION AND QUANTITY

Size	1825		2220		2225	
Chip Thickness	1.60±0.20 2.00±0.20	2.50±0.30	1.40±0.15 1.60±0.20 2.00±0.20	2.50±0.30	1.60±0.20 2.00±0.20	2.50±0.30
A_0	<6.80	<6.80	<5.80	<5.80	<6.80	<6.80
B_0	<5.30	<5.30	<6.50	<6.50	<6.50	<6.50
T	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10
K_0	<2.50	<3.10	<2.50	<3.10	<2.50	<3.10
W	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20
P_0	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
$10xP_0$	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20
P_1	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P_2	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D_0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0
D_1	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05
Unit :	mm	mm	mm	mm	mm	mm

9.2. REEL DIMENSIONS

Size	0201, 0402, 0603, 0805, 1206, 1210		1808, 1812, 1825, 2220, 2225
Reel size	7”	13”	7”
C	13.0 +0.5/-0.2	13.0 +0.5/-0.2	13.0 +0.5/-0.2
W_1	8.4 +1.5/-0	8.4 +1.5/-0	8.4 +1.5/-0
W	14.4max	14.4max	shall accommodate tape width without interference
A	178.0 ±0.10	330.0 ±1.0	178.0 ±0.10
N	60.0 +1.0/-0	100 ±1.0	60.0 +1.0/-0

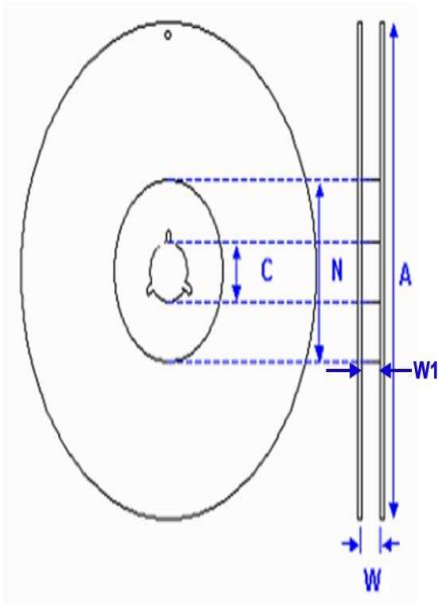


Fig. 9.3 The dimension of reel

10. APPLICATION NOTES

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended :

Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped product should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 12 months after shipment and checked the solderability before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

PREHEAT

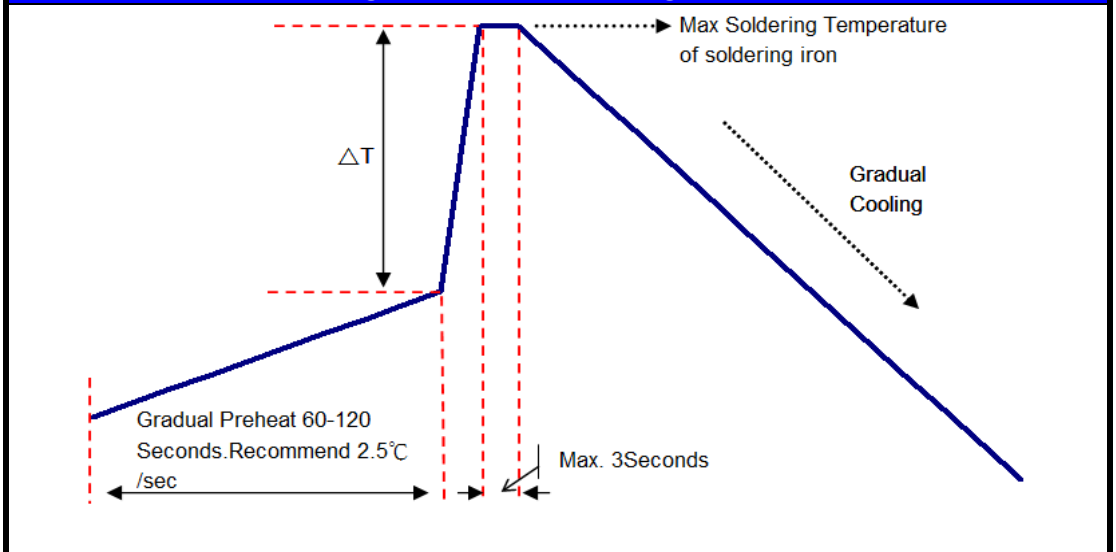
In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required. The rate of preheat should not exceed 3°C per second.

SOLDERING

Use middy activated rosin RA and RMA fluxes do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

a.) Hand soldering :

Fig. 10.1 Hand Soldering Profile



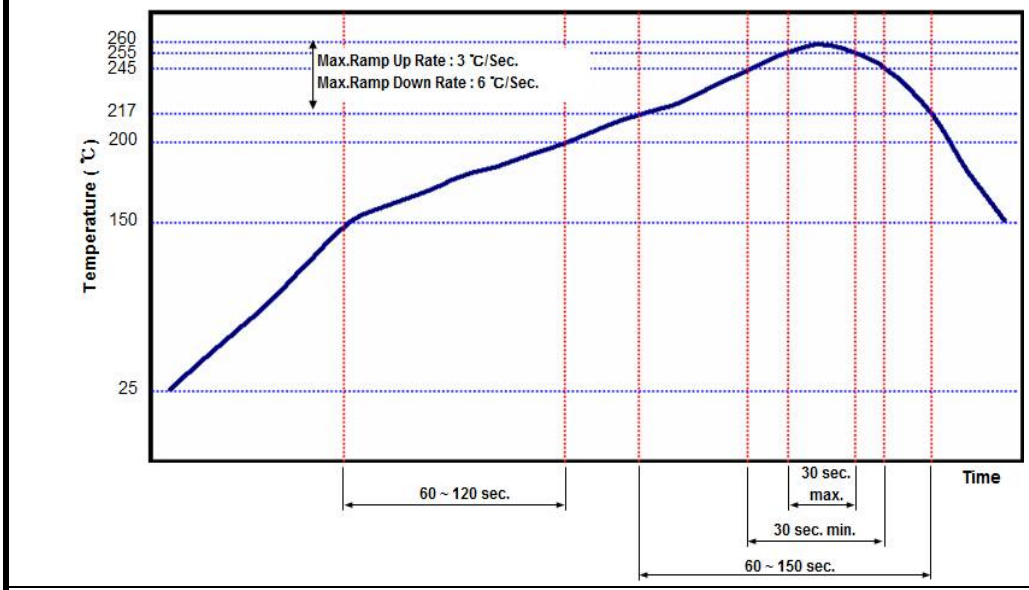
Chip Size	Pre-Heat temp.	ΔT	Max. soldering iron temp.
≤1206	≥150°C	≤150°C	≤350°C
1210~2225	≥150°C	≤130°C	≤280°C

* Soldering iron tip diameter ≤1.0 mm and wattage max. 20W.
* The Capacitors shall be pre-heated and that the temperature gradient between the devices and the tip of the soldering iron.
* The required amount of solder shall be melted on the soldering tip.
* The tip of iron should not contact the ceramic body directly.
* The Capacitors shall be cooled gradually at room temperature after soldering.
* Forced air cooling is not allowed.

10. APPLICATION NOTES

b.) Reflow soldering :

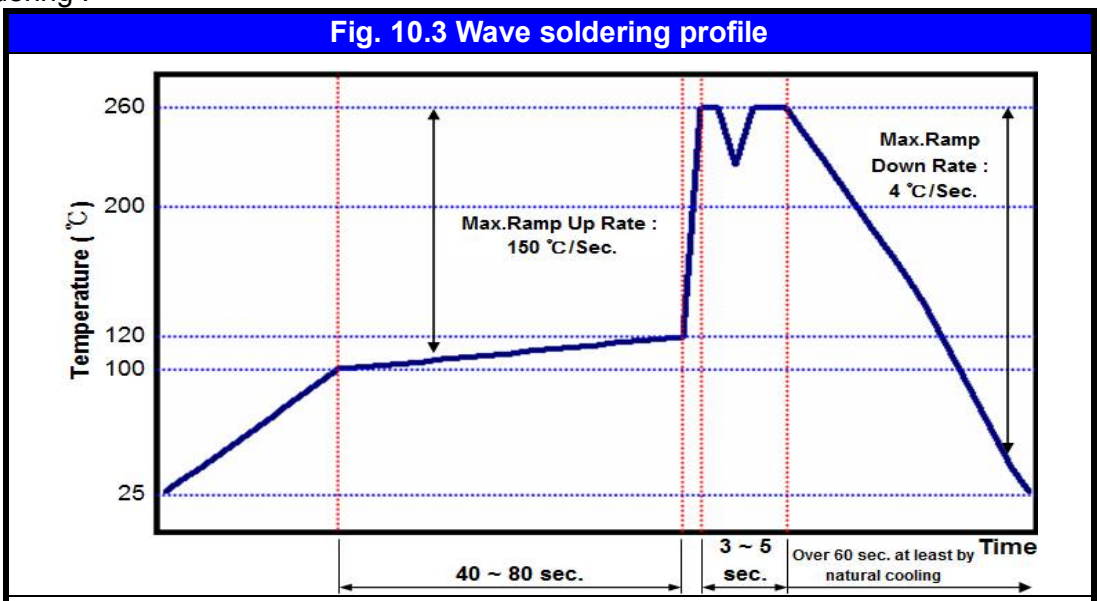
Fig. 10.2 Reflow soldering profile



For Sn/Ag/Cu Series solder paste (Pb-Free)

c.) Wave soldering :

Fig. 10.3 Wave soldering profile



For Sn/Ag/Cu Series solder paste (Pb-Free)

Soldering conditions :

Class I :

Size Inch (mm)	Temper. Cher.	Capacitance	Condition	
			Wave	Reflow
≤0402 (1005)	All Class I	All	X	O
0603 (1608)	All Class I	All	O	O
0805 (2012)	All Class I	All	O	O
1206 (3216)	All Class I	All	O	O
≥1210 (3225)	All Class I	All	X	O

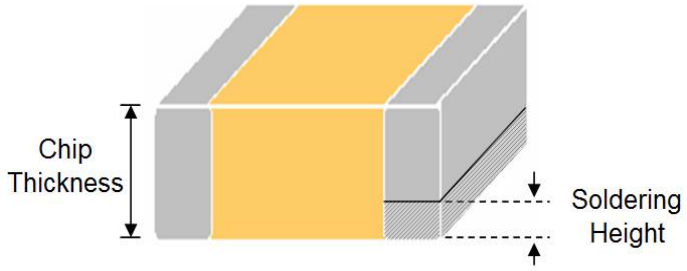
10. APPLICATION NOTES

Soldering conditions :
Class II :

Size Inch (mm)	Temper. Cher.	Capacitance	Condition	
			Wave	Reflow
≤0402 (1005)	All Class II	All	X	O
0603 (1608)	All Class II	Cap. <2.2μF	O	O
		Cap. ≥2.2μF	X	O
0805 (2012)	All Class II	Cap. <4.7μF	O	O
		Cap. ≥4.7μF	X	O
1206 (3216)	All Class II	Cap. <4.7μF	O	O
		Cap. ≥4.7μF	X	O
≥1210 (3225)	All Class II	All	X	O

Soldering height :

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less.
(Reference from IPC-610E)



COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

INNER CONSTRUCTION OF OPEN-MODE DESIGN

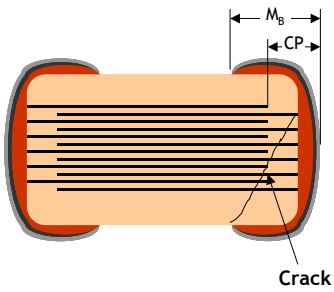


Fig. 10-4 Normal design ($CP<M_B$) – circuit leakage during cracking.

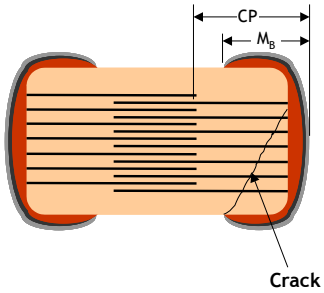


Fig. 10-5 Open-mode design ($CP>M_B$) – circuit open during cracking.

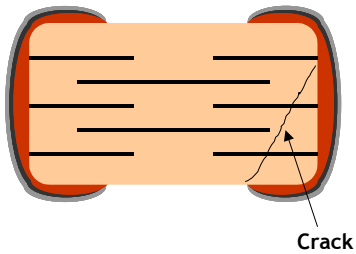


Fig. 10-6 Floating design (one kind of open-mode design)– circuit open during cracking.